

Abstract**Method for Electroless Deposition of a Metal Layer on Selected Portions of a Substrate**

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The present invention relates to a method for electroless deposition of a metal layer on selected portions of a substrate. A preferred form of the invention relates to a method of depositing a desired metal layer, by electroless deposition, on one or more selected portions of an indium tin oxide (ITO) surface of a substrate. These selected portions are typically transparent conductive paths of ITO. The method includes a number of steps. The first step involves applying a masking layer onto the surface, the masking layer has one or more apertures formed therein so as to expose the one or more selected portions of the surface. The next step involves exposing the one or more selected portions of the surface to a colloidal suspension of catalytic particles adapted to adsorb to the substrate surface and to enhance deposition of the desired metal layer thereon. The next step involves exposing the one or more selected portions of the surface to an ionic solution containing ions of the desired metal to enable formation of the metal layer.

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[Figure 1]